

**STMP3770XXBJEA2N**  
(Not Recommended for New Designs)

PMP CONTROLLER

**Package**

[VFBGA100](#)

VFBGA100, plastic, very thin fine-pitch ball grid array; 100 balls; 0.5 mm pitch; 6 mm x 6 mm x 0.66 mm body



Image not available

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### Buy Options

STMP3770XXBJEA2N  
935317037557  
NOT RECOMMENDED FOR NEW DESIGNS

TRAY-Tray, Bakeable, Multiple in Drypack  
Min. Package Quantity: 429  
Lead Time: 15 weeks

### Operating Characteristics

No information available

### Environmental Information

Material Declaration	Pb-Free	EU RoHS	Halogen Free	RHF Indicator	2nd Level Interconnect	REACH SVHC	Weight (mg)
<a href="#">STMP3770XXBJEA2N</a> (935317037557)	Yes	Yes	Yes	D	e1	<a href="#">REACH SVHC</a>	64.6

### Quality Information

Material Declaration	Safe Assure Functional Safety	Moisture Sensitivity Level (MSL)	Peak Package Body Temperature (PPT) (C°)	Maximum Time at Peak Temperatures (s)
		Lead Free Soldering	Lead Free Soldering	Lead Free Soldering
<a href="#">STMP3770XXBJEA2N</a> (935317037557)	No	3	260	40

### Shipping Information

Part Number	Harmonized Tariff (US) <a href="#">Disclaimer</a>	Export Control Classification Number (US)
<a href="#">STMP3770XXBJEA2N</a> (935317037557)	854231	5A992

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